

REV.	DESCRIPTION OF REVISIONS	APPR.	CHKD.	DRAW.	DATE
△	新开			Zoey	2006.3.10
△	增加主体塑性变形尺寸			huabo	2020.9.17
△	Original Model C713-1			huabo	2023.10.26

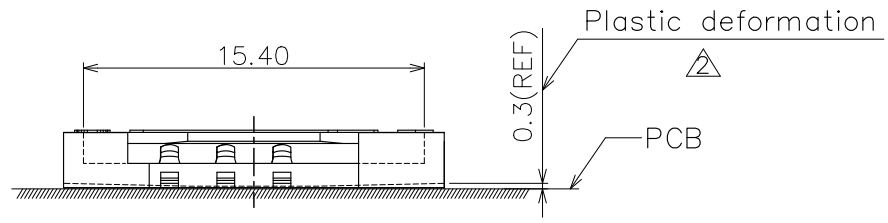
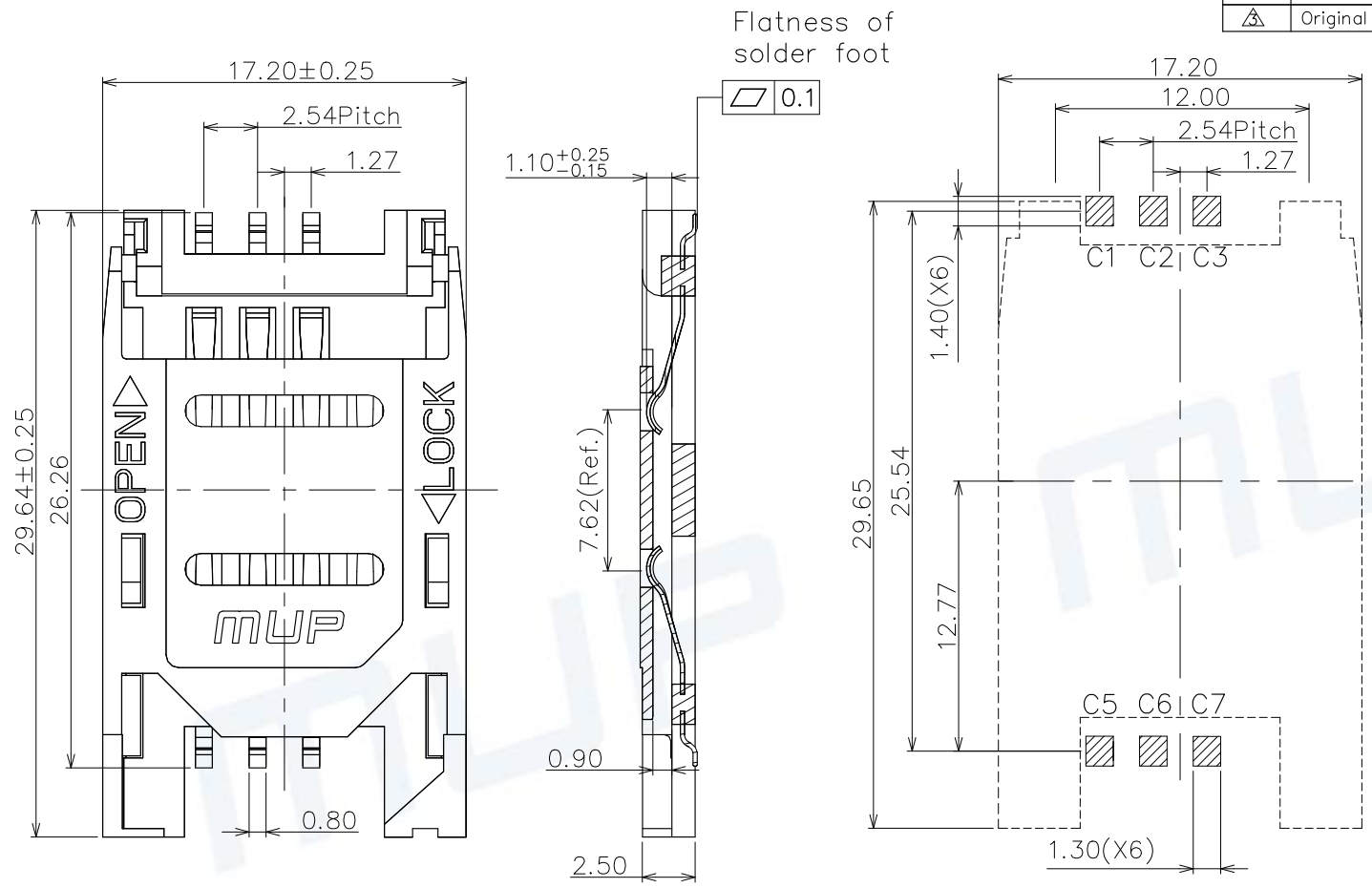
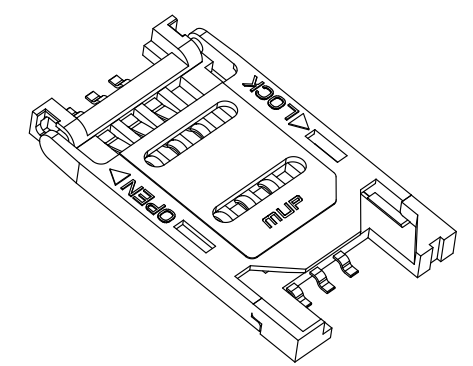
TECHNICAL CHARACTERISTICS

1.General Characteristics
Durability:5,000 cycles min.

2.Electrical Characteristics
Contact resistance:Initial: 50mΩ Max.
After Test: 100mΩ Max.
Insulation resistance:>1000MΩ/500V DC

3.Solderability
IR reflow: 250°C,5sec.Max
Manual soldering: 370°C,3sec.Max

4.Environmental Characteristics
Operating temperature: -40°C~+85°C
Operating humidity: 10%~+95%RH



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	COVER	1	Hi-temp Thermoplastic	Black UL94V-0
3	DATA CONTACT	6	Copper Alloy	Contact area:5u"Au plated

Unless otherwise specified, other tolerance are:

X	±0.35	X*	±5°
X.X	±0.25	X.X*	±4°
X.XX	±0.15	X.XX*	±3°
X.XXX	±0.10	X.XXX*	±2°

MUP® MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**

MODEL NO: **MUP-C7013-01**

TYPE: **H2.5 without post 6p**

PROJ.	UNIT	SCALE	DRAWN	Zoey	Mar.10.2006	DWG NO.:	DWG-C7013-01-01	
	mm	1:1	CHECKED	Jimmy	Mar.10.2006	SHEET	1/1	REVISION
			APPROVAL	Simon	Mar.10.2006		3	



CUSTOMER DRAWING